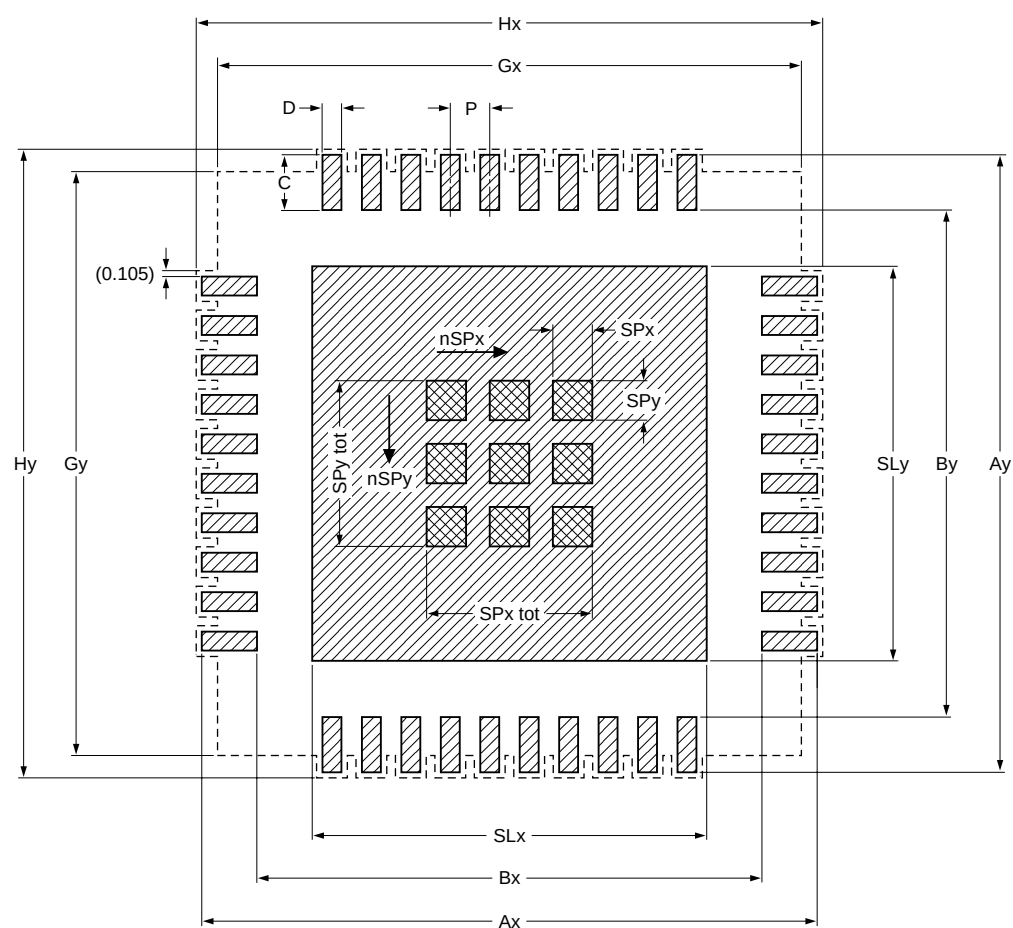


Footprint information for reflow soldering of HVQFN20 package

SOT662-1



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
2	2

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.650	6.000	6.000	3.800	3.800	1.100	0.350	3.000	3.000	1.800	1.800	0.650	0.650	5.300	5.300	6.250	6.250